

Features

- 0606 0.55mm SMD LED
- High Brightness
- AllnGaP / InGaN Technology
- Small package
- High reliability
- Clear Lens

Applications

- Consumer Electronics
- Wearables
- Automobile After Market
- Industrial Equipment

Description

The IN-S66DAT5R5B is a dual color 0606 package with versatile design capabilities. It is a PCB type LED which can be used in various applications.

Recommended Solder Pattern

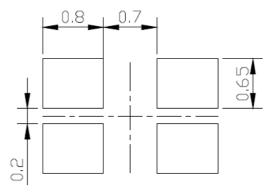
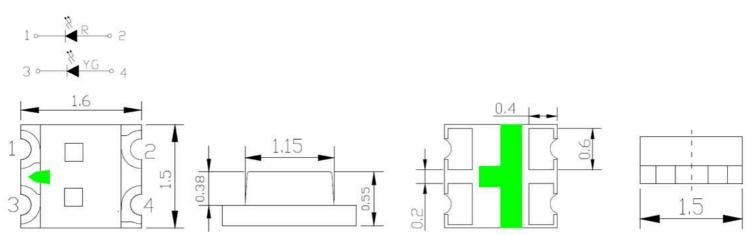


Figure 1. IN-S66DAT5R5B Solder Pattern



Package Dimensions in mm

Figure 2. IN-S66DAT5R5B Package Dimensions



Absolute Maximum Rating at 25°C (Note 1)

	Product	Emission Color	P₀ (mW)	l⊧ (mA)	I _{FP} * (mA)	V _R (V)	Top (°C)	Тѕт (⁰С)	
IN-Se		Red	75	25	70		-30°C~+85°C	-40°C~+90°C	
	IN-S66DAT5R5B	Blue	75	25	70	5			

Notes

1. Condition for IFP is pulse of 1/10 duty and 0.1msec width

ESD Precaution

ATTENTION: Electrostatic Discharge (ESD) protection

The symbol above denotes that ESD precaution is needed. ESD protection for GaP and AlGaAs based chips is necessary even though they are relatively safe in the presence of low static-electric discharge. Parts built with AlInGaP, GaN, or/and InGaN based chips are STATIC SENSITIVE devices. ESD precaution must be taken during design and assembly. If manual work or processing is needed, please ensure the device is adequately protected from ESD during the process.

Please be advised that normal static precautions should be taken in the handling and assembly of this device to prevent damage or degradation which may be induced by electrostatic discharge (ESD).

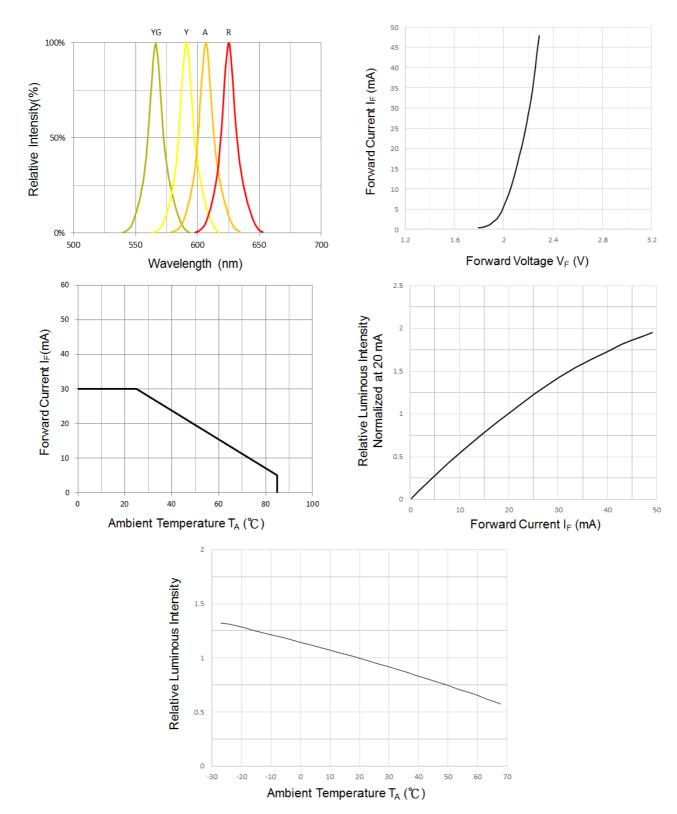
Electrical Characteristics $T_A = 25C$ (Note 1)

	Emission		Vf((V)	λ(nm)			Viewing Angel	l*∨(mcd)
Product	Color	I⊧(mA)	typ.	max	λD	λP	∆∆	2 <i>θ</i> 1/2	typ.
IN-S66DAT5R5B	Red	Red 5	2.2	2.6	622	630	20	120	35
11-300DA13K3B	Blue	5	3.2	3.6	467	470	35	120	56

Notes

1. Performance guaranteed only under conditions listed in above tables.

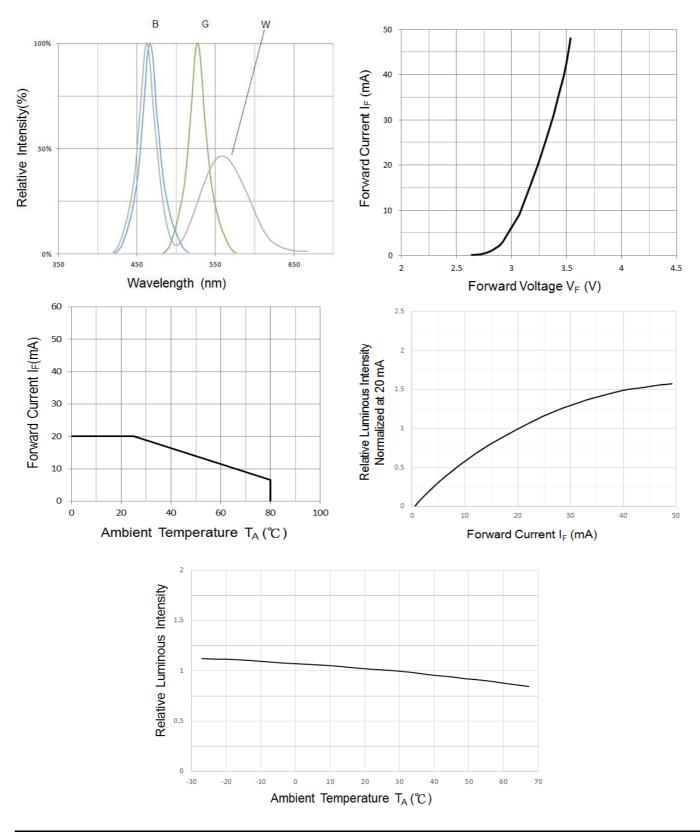




Typical Characteristic Curves – YG, Y, A, R

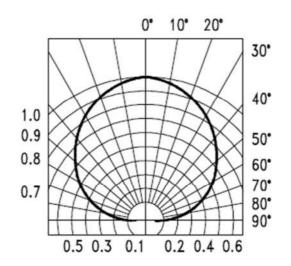


Typical Characteristic Curves – B, G, W





Typical Characteristic Curves – Radiation Pattern

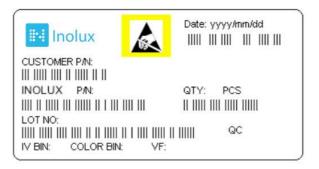


Ordering Information

Product	Emission Color	Test Current I _F (mA)	Luminous Intensity I _V (mcd) (Typ.)	Forward Voltage V _F (V) (Typ.)	Orderable Part Number
IN-S66DAT5R5B	Red	5	35	2.2	IN-S66DAT5R5B
114-300DA13K3B	Blue	5	56	3.2	IN-300DA13K3B



Label Specifications



Inolux P/N:

I	Ν	-	S	6	6	D	А	Т	5		R	5		В	-	Х	Х	Х	Х
			Material	Pacl	kage	Varia	ation	Orientation	Current	Lens	Color	Current	Lens	Color			Custor Stam		
	nolux SMD		S = PCB Type	661		L.6 x 1. 5mm	.5 x	T = Top Mount	5=5mA	(Blank) = Clear	R=630 nm	5=5mA	(Blank) = Clear	B=470 nm					

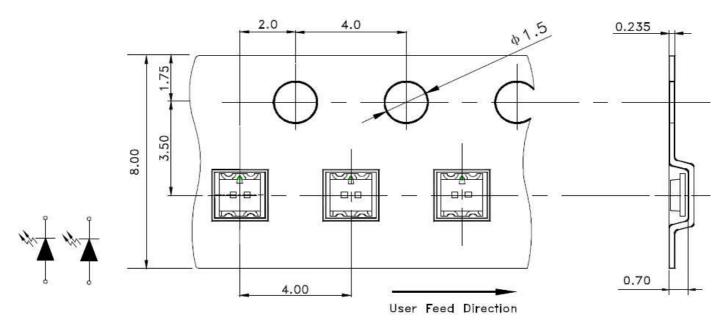
Lot No.:

Z	2	0	1	7	01	24	001
Internal		Year (2017	2018	Month	Date	Serial	
Tracker			, 2010,)	wonth	Date	Serial	

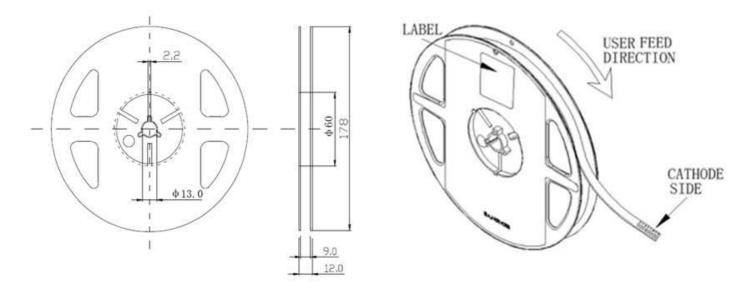


Packaging Information: 4000pcs Per Reel

Tape Dimension

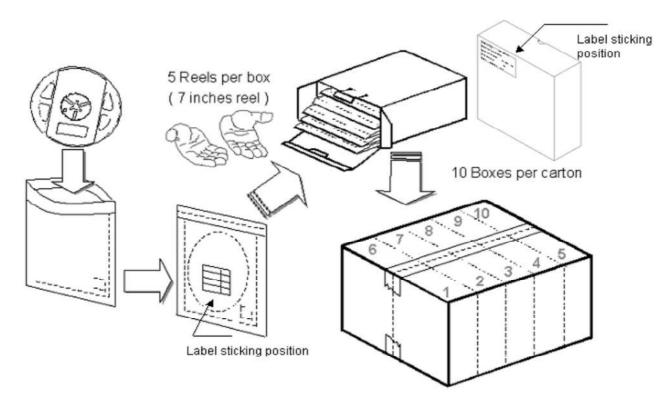


Reel Dimension





Packing Dimension



5 boxes per carton are available depending on shipment quantity.

	Specification	Material	Quantity
Carrier tape	Per EIA 481-1A specs	Conductive black tape	4000pcs per reel
Reel	Per EIA 481-1A specs	Conductive black	
Label	IN standard	Paper	
Packing bag	220x240mm	Aluminum laminated bag/ no-zipper	One reel per bag
Carton	IN standard	Paper	Non-specified

Others:

Each immediate box consists of 5 reels. The 5 reels may not necessarily have the same lot number or the same bin combinations of Iv, λ_D and Vf. Each reel has a label identifying its specification; the immediate box consists of a product label as well.

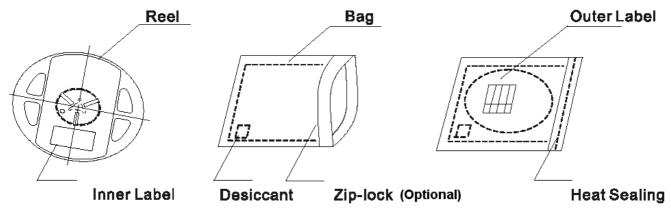


Dry Pack

All SMD optical devices are **MOISTURE SENSITIVE**. Avoid exposure to moisture at all times during transportation or storage. Every reel is packaged in a moisture protected anti-static bag. Each bag is properly sealed prior to shipment.

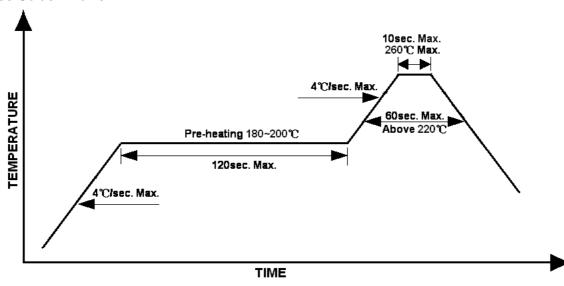
Upon request, a humidity indicator will be included in the moisture protected anti-static bag prior to shipment.

The packaging sequence is as follows:



Reflow Soldering

- Recommended tin glue specifications: melting temperature in the range of 178~192 °C
- The recommended reflow soldering profile is as follows (temperatures indicated are as measured on the surface of the LED resin):



Lead-free Solder Profile



Precautions

- Avoid exposure to moisture at all times during transportation or storage.
- Anti-Static precaution must be taken when handling GaN, InGaN, and AlInGaP products.
- It is suggested to connect the unit with a current limiting resistor of the proper size. Avoid applying a reverse voltage.
- Avoid operation beyond the limits as specified by the absolute maximum ratings.
- Avoid direct contact with the surface through which the LED emits light.
- If possible, assemble the unit in a clean room or dust-free environment.

Reworking

- Rework should be completed within 5 seconds under 260 °C.
- The iron tip must not come in contact with the copper foil.
- Twin-head type is preferred.

Cleaning

Following are cleaning procedures after soldering:

- An alcohol-based solvent such as isopropyl alcohol (IPA) is recommended.
- Temperature x Time should be 50°C x 30sec. or <30°C x 3min
- Ultra sonic cleaning: < 15W/ bath; bath volume ≤ 1liter
- Curing: 100 °C max, <3min

Cautions of Pick and Place

- Avoid stress on the resin at elevated temperature.
- Avoid rubbing or scraping the resin by any object.
- Electro-static may cause damage to the component. Please ensure that the equipment is properly grounded. Use of an ionizer fan is recommended.



Reliability

Item		Standards	Conditions				
Item	failures	Reference					
	For all reliability	J-STD-020	1.) Baking at 85℃ for 24hrs				
Precondition	monitoring tests according		2.) Moisture storage at 85℃/ 60% R.H. for				
	to JEDEC Level 2		168hrs				
	1Q/ 1/ 22/ 0	JESD22-B102-B	Accelerated aging 155℃/ 24hrs				
Solderability		And CNS-5068	Tinning speed: 2.5+0.5cm/s				
			Tinning: A: 215℃/ 3+1s or B: 260℃/ 10+1s				
		CNS-5067	Dipping soldering terminal only				
Resistance to			Soldering bath temperature				
soldering heat			A: 260+/-5℃; 10+/-1s				
			B: 350+/-10℃; 3+/-0.5s				
	1Q/ 1/ 40/ 0	CNS-11829	1.) Precondition: 85℃ bakin g for 24hrs				
Operating life test			85℃/ 60%R.H. for 168hrs				
			2.) Tamb25℃; IF=20mA; duration 1000hrs				
High humidity,	1Q/ 1/ 45/ 0	JESD-A101-B	Tamb: 85℃				
high temperature			Humidity: 85% R.H., IF=5mA				
bias			Duration: 1000hrs				
High temperature	1Q/ 1/ 20	IN specs.	Tamb: 55℃				
bias			IF=20mA				
5183			Duration: 1000hrs				
	1Q/ 1/ 40/ 0		Tamb25℃, If=20mA,, Ip=100mA, Duty				
Pulse life test			cycle=0.125 (tp=125 μ s,T=1sec)				
			Duration 500hrs)				
	1Q/ 1/ 76/ 0	JESD-A104-A	A cycle: -40 degree C 15min; +85 degree C				
Temperature		IEC 68-2-14, Nb	15min				
cycle			Thermal steady within 5 min				
Cycle			300 cycles				
			2 chamber/ Air-to-air type				
High humidity	1Q/ 1/ 40/ 0	CNS-6117	60+3℃				
storage test			90+5/-10% R.H. for 500hrs				
High temperature	1Q/ 1/ 40/ 0	CNS-554	100+10℃ for 500hrs				
storage test							
Low temperature	1Q/ 1/ 40/ 0	CNS-6118	-40+5℃ for 500hrs				
storage test							



Revision History

Changes since last revision	Page	Version No.	Revision Date
Initial Release		V1.0	05-12-2017

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